

Features

- High speed switching
- Reliable body diode
- All parts tested to greater than 1,400V

Switch mode power supplies, UPSInduction heating and welding

• High voltage DC/DC converters

• Avalanche tested to 400mJ*

Benefits

Applications

- Lower capacitance
- Higher system efficiency
- · Easy to parallel

Solar Inverters

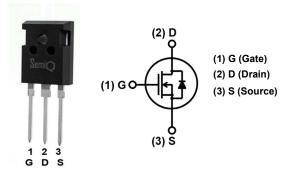
Motor drives

• EV charging stations

GP2T040A120U

V _{DS}	1200 V
R _{DS,on}	37 mΩ
I _{D (TC=25C)}	63 A
T _j ,max	175°C

Package



Part #	Package	Marking
GP2T040A120U	TO-247-3L	2T040A120



Maximum Ratings, at Ti=25°C, unless otherwise specified

Characteristics	Symbol	Conditions	Values	Unit
Drain-Source Voltage	V _{rated}	V _{GS} =0V, I _{DS} =1µA	1200	V
Continuous Drain Current		T _C =25 °C, T _j =175 °C	63	
	I _D	T _C =100 °C, T _j =175 °C	47	Α
Pulsed Drain Current	I _{D,pulse} *	T _C =25°C	160	
Gate Source Voltage	V _{GSmax}		-10/25	V
Gale Source vollage	V _{GSop}	Recommended operational	-5/20	v
Power Dissipation	P _{tot}	T _C =25°C	322	W
Operating & Storage Temperature	T _{j,} T _{storage}	Continuous	-55175	°C
Single Pulse Avalanche Energy	E _{AS}	L=1.0mH, I _{AS} =28.3A, V=50V	400	mJ

Thermal Characteristics

Characteristics	Symbol Conditions	Values			Unit	
Characteristics	Symbol	Conditions	min.	typ.	max.	
Thermal Resistance, Junction to Case	R _{thJC}		-	0.38	0.47	
Thermal Resistance, Junction to Ambient	R_{thJA}		-	-	40.0	°C/W

* Pulse width is limited by Tj_{max}

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Static Electrical Characteristics, at T_j =25°C, unless otherwise specified

Characteristics	Symphol	Conditions -	Values			11
Characteristics	Symbol		min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	I _{DS} =1mA	1200	-	-	V
Zero Gate Voltage Drain Current		V _{DS} =1200V, V _{GS} =0V	-	0.1	1.0	
	I _{DSS}	V _{DS} =1200V, V _{GS} =0V, T _j =175°C	-	1	-	μΑ
Cata Sauraa Laakaga Current	I _{GSS+}	V _{GS} =20V, V _{DS} =0V	-	<+10	100	n A
Gate-Source Leakage Current	I _{GSS-}	V _{GS} =-5V, V _{DS} =0V	-	>-10	-100	- nA
	V _{GS(th)}	V _{GS} =V _{DS} , I _{DS} =10mA	2	2.4	4	v
Gate Threshold Voltage		$V_{GS}=V_{DS}$, $I_{DS}=10$ mA, $T_j=125$ °C	-	1.8	-	
		$V_{GS}=V_{DS}$, $I_{DS}=10$ mA, $T_j=175$ °C	-	1.6	-	
		V _{GS} =20V, I _{DS} =40A	-	37	52	
Drain Source On Desistance	Б	V _{GS} =20V, I _{DS} =20A	-	35	45	- mΩ
Drain-Source On-Resistance	R _{DSon}	V _{GS} =20V, I _{DS} =40A, T _j =125°C	-	56	-	
		V _{GS} =20V, I _{DS} =40A, T _j =175°C	-	73	-	1
Transconductance	9 _{fs}	V _{DS} =20V, I _{DS} =40A	-	16	-	S
Gate Input Resistance	R _G	f=1MHz, V _{AC} =25mV, D-S Short	-	1.9	-	Ω

AC Electrical Characteristics, at $T_j\mbox{=}25\mbox{°C},$ unless otherwise specified

Characteristics	Symbol	Conditions	Values			Unit
Characteristics	Symbol	Conditions	min.	typ.	max.	
Input Capacitance	C _{ISS}	N/ -0)/	-	3192	-	
Output Capacitance	C _{OSS}	−V _{GS} =0V, −V _{DS} =1000V,	-	132	-	pF
Reverse Transfer Capacitance	C _{RSS}	f=200kHz, V _{AC} =25mV	-	7	-	
Coss Stored Energy	E _{oss}		-	77	-	μJ
Turn-On Switching Energy	E _{ON}	V _{DD} =800V, I _{DS} =40A,	-	1087	-	
Turn-Off Switching Energy	E _{OFF}	R _{G(ext)} =2.5, V _{GS} =-5/+20V, L=273µH,	-	86	-]
Total Switching Energy	E _{TOT}	FWD=GP2T040A120U	-	1173	-]
Turn-On Switching Energy	E _{ON}	V _{DD} =800V, I _{DS} =40A,	-	888	-	
Turn-Off Switching Energy	E _{OFF}	R _{G(ext)} =2.5, V _{GS} =-5/+20V, L=273µH,	-	94	-	μJ
Total Switching Energy	E _{TOT}	FWD=GP3D020A120A	-	982	-	7
Turn-On Delay Time	t _{D(on)}	V _{DD} =800V, I _{DS} =40A,	-	15	-	
Rise Time	t _R	R _{G(ext)} =2.5, V _{GS} =-5/+20V,	-	14	-]
Turn-Off Delay Time	t _{D(off)}	L=273µH,	-	22	-	- ns
Fall Time	t _F	FWD=GP2T040A120U	-	14	-]
Total Gate Charge	Q _G		-	118	-	
Gate to Source Charge	Q _{GS}	V _{DD} =800V, I _{DS} =40A, V _{GS} =-5/+20V	-	53	-	nC
Gate to Drain Charge	Q _{GD}		-	10	-]

Body Diode Characteristics, at Tj=25°C, unless otherwise specified

Characteristics	Symbol	Conditions	Values			Unit
Characteristics	ristics Symbol Conditions		min.	typ.	max.	Unit
Max Continuous Diode Fwd Current	I _S	V _{GS} =-5V, T _C =25°C	-	-	74	A
Diode Forward Voltage	V _{SD}	V _{GS} =-5V, I _{SD} =20A	-	3.8	-	V
Reverse Recovery Time	t _{RR}	I _{SD} =40A, V _R =800V, V _{GS} =-5V,	-	28	-	ns
Reverse Recovery Charge	Q _{RR}	$di_{\rm F}/dt=3.2A/ns$	-	284	-	nC
Peak Reverse Recovery Current	I _{RRM}		-	18	-	A

GP2T040A120U

Typical Performance

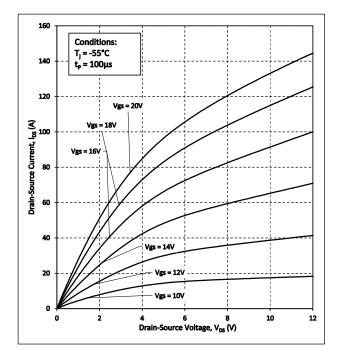


Figure 1. Output Characteristics T_i = -55°C

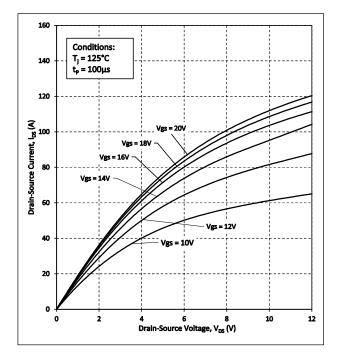


Figure 3. Output Characteristics T_i = 125°C

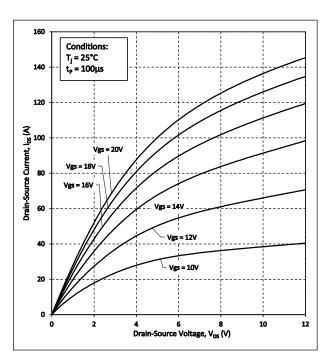


Figure 2. Output Characteristics T_j = 25°C

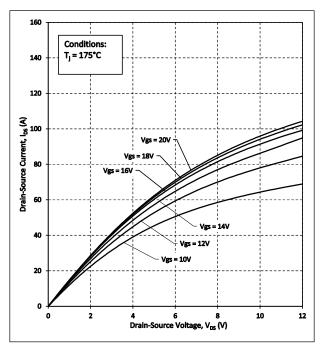


Figure 4. Output Characteristics T_i = 175°C

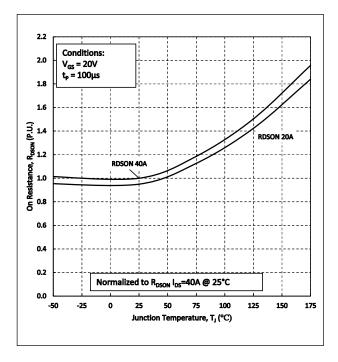


Figure 5. Normalized On-Resistance vs. Temperature

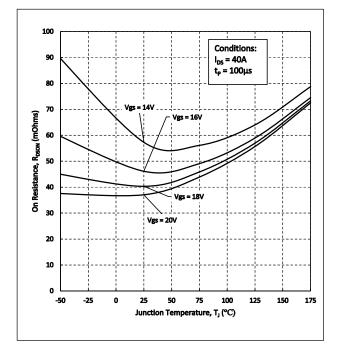


Figure 7. On-Resistance vs. Temperature For Various Gate Voltages

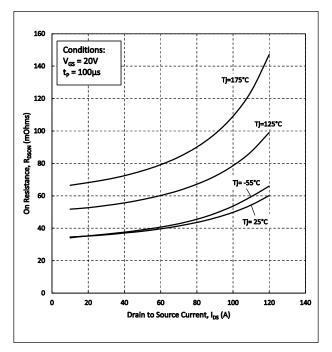


Figure 6. On-Resistance vs. Drain Current For Various Temperature

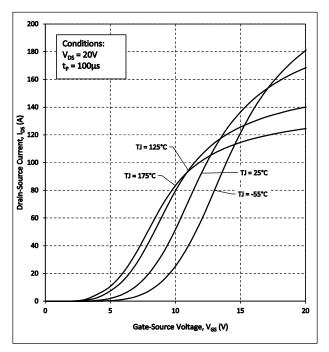


Figure 8. Transfer Characteristic for Various Junction Temperatures

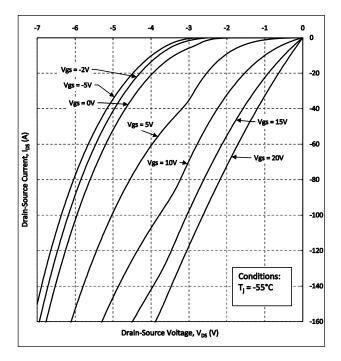


Figure 9. Body Diode Characteristics at T_i = -55°C

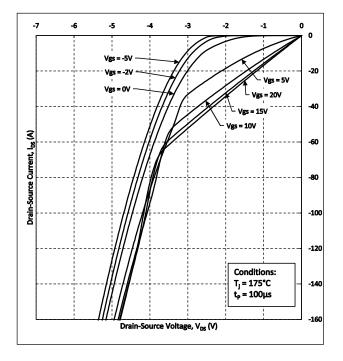


Figure 11. Body Diode Characteristics at T_i = 175°C

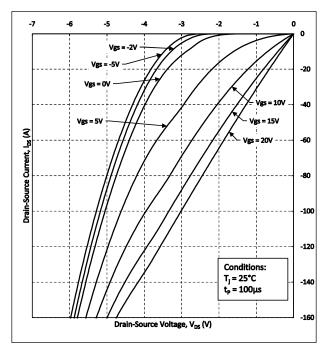


Figure 10. Body Diode Characteristics at T_i = 25°C

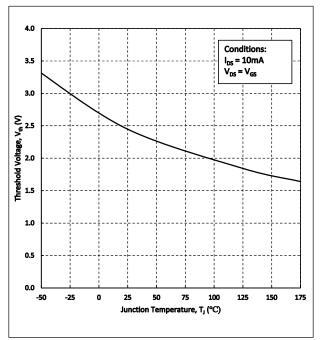


Figure 12. Threshold Voltage vs. Temperature

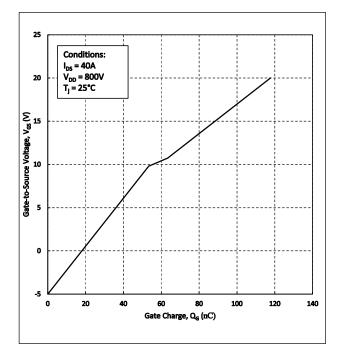


Figure 13. Gate Charge Characteristics

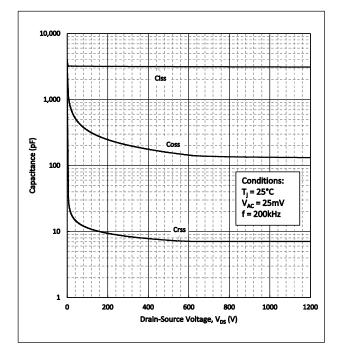


Figure 15. Capacitance vs Drain-Source Voltage

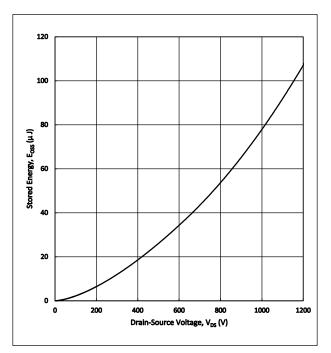


Figure 14. Output Capacitor Stored Energy

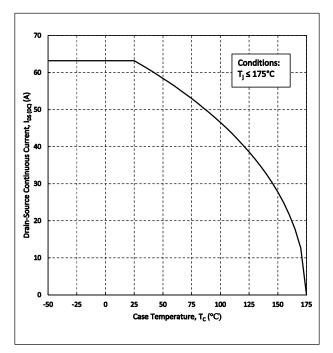


Figure 16. Continuous Drain Current Derating vs. Case Temperature

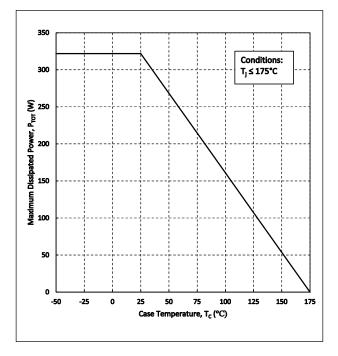


Figure 17. Maximum Power Dissipation Derating vs Case Temperature

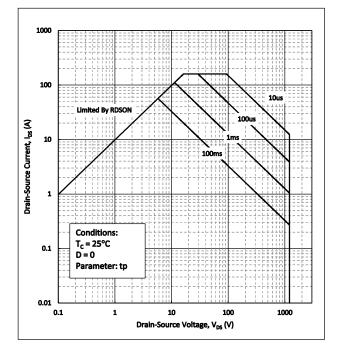


Figure 19. Safe Operating Area

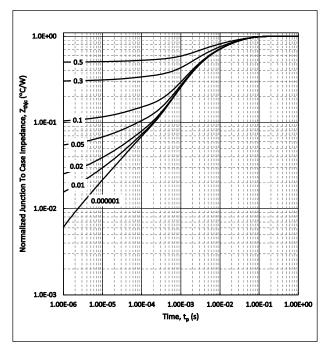


Figure 18. Transient Thermal impedance (Junction to Case)

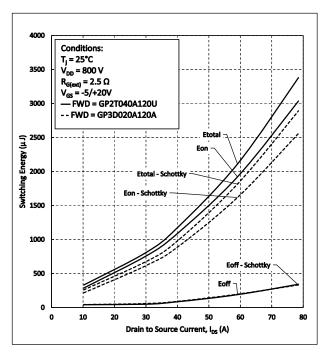


Figure 20. Clamped Inductive Switching Energy vs. Drain Current

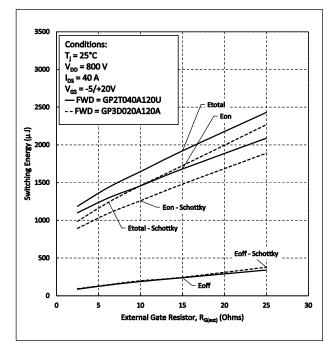


Figure 21. Clamped Inductive Switching Energy vs. $$R_{G(ext)}$$

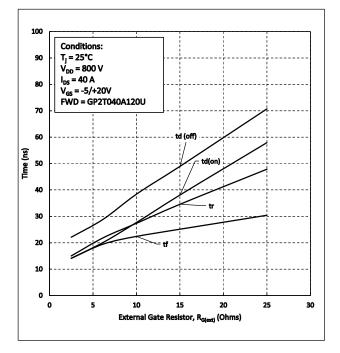


Figure 23. Switching Times vs R_{G(ext)}

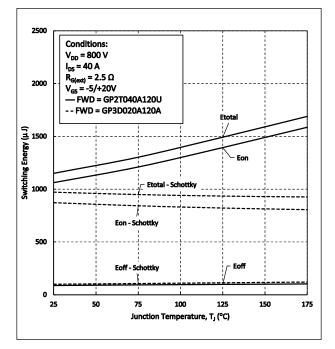


Figure 22. Clamped Inductive Switching Energy vs. Temperature

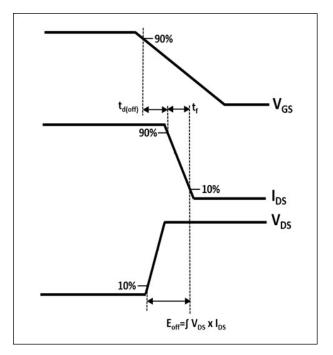


Figure 24. Turn-off Transient Definitions

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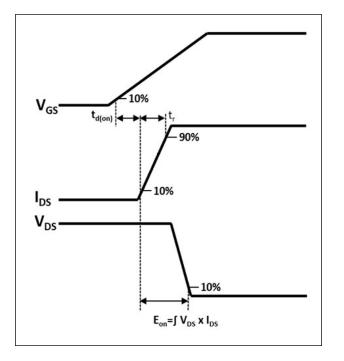


Figure 25. Turn-on Transient Definitions

A

-A2

-A 1

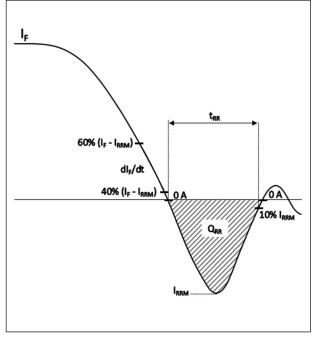
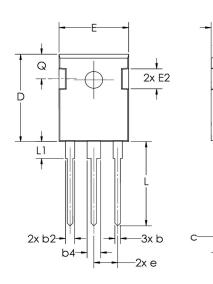
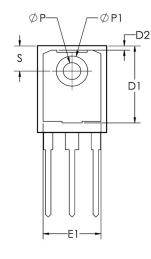


Figure 26. Reverse Recovery Definitions

Package Dimensions TO-247-3L





Sym	Millimeters		Incl	hes
Sym	Min	Max	Min	Max
Α	4.70	5.31	0.185	0.209
A1	2.21	2.59	0.087	0.102
A2	1.50	2.49	0.059	0.098
b	0.99	1.40	0.039	0.055
b2	1.65	2.39	0.065	0.094
b4	2.59	3.43	0.102	0.135
с	0.38	0.89	0.015	0.035
D	20.80	21.46	0.819	0.845
D1	13.08	17.65	0.515	0.695
D2	0.51	1.35	0.020	0.053
E	15.49	16.26	0.610	0.640
E1	13.46	14.16	0.530	0.557
E2	3.43	5.49	0.135	0.216
е	5.44 BSC		0.214	BSC
L	19.81	20.32	0.780	0.800
L1	4.10	4.50	0.161	0.177
ØР	3.56	3.66	0.140	0.144
ØP1	7.06	7.39	0.278	0.291
Q	5.39	6.20	0.212	0.244
S	6.04	6.30	0.238	0.248

GP2T040A120U

Notes

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented March, 2013. RoHS Declarations for this product can be obtained from the Product Documentation sections of www.SemiQ.com.

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